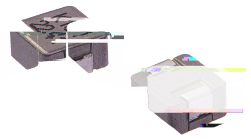
MDA Series

SMD Low Profile High Current Molded Inductor

Size 5030



FEATURES

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- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
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- 100% Lead(Pb)-Free and RoHS compliant.
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APPLICATION

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- HVAC
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- Audio subsystem
- Digital instrument cluster
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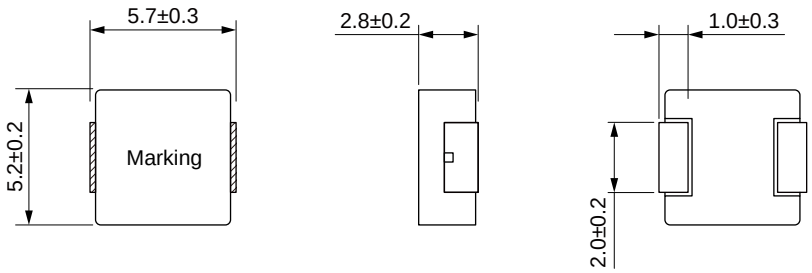
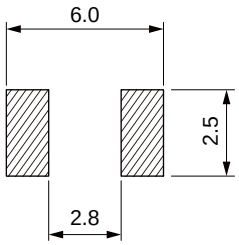
Dimensions: [mm]



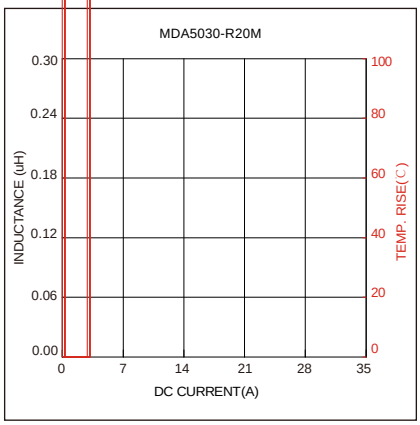
Land Pattern: [mm]

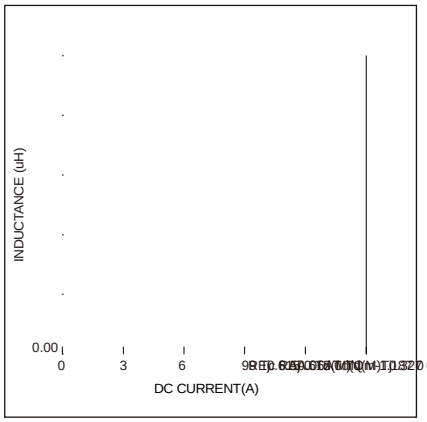


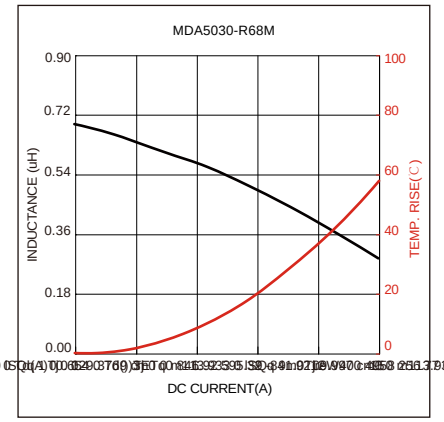
Electrical Properties:

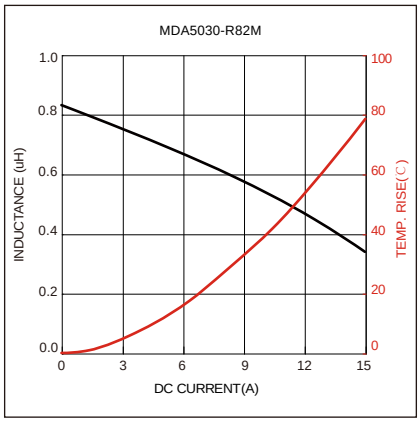
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Current Typ. (A)	Current Max. (A)	DC Resistance Typ.	DC Resistance Max.
MDA5030-R20M	0.20	±20%	14.0	13.0	20.0	16.0	3.60	3.90
MDA5030-R47M	0.47	±20%	13.5	12.0	10.0	9.0	5.20	6.00
MDA5030-R68M	0.68	±20%	12.5	11.0	9.0	8.0	7.40	8.50
MDA5030-R82M	0.82	±20%	10.0	9.0	8.8	7.7	8.00	9.20
MDA5030-1R0M	1.00	±20%	9.0	8.0	8.5	7.5	10.5	12.0
MDA5030-1R5M	1.50	±20%	8.0	7.0	7.5	6.5	13.6	15.7
MDA5030-2R2M	2.20	±20%	7.0	6.5	6.5	5.8	21.6	25.0
MDA5030-3R3M	3.30	±20%	6.3	5.8	6.0	5.3	28.0	33.0
MDA5030-4R7M	4.70	±20%	5.5	4.8	5.3	4.6	38.0	44.0
MDA5030-5R6M	5.60	±20%	5.0	4.3	4.6	4.0	50.0	58.0

Typical Electrical Characteristics:

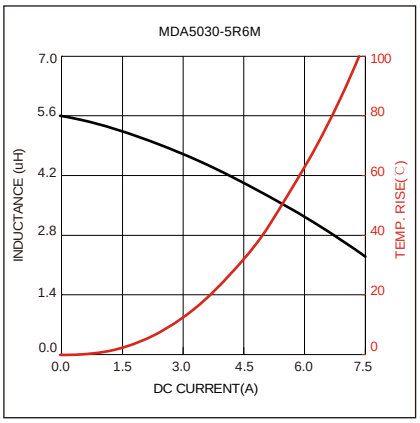


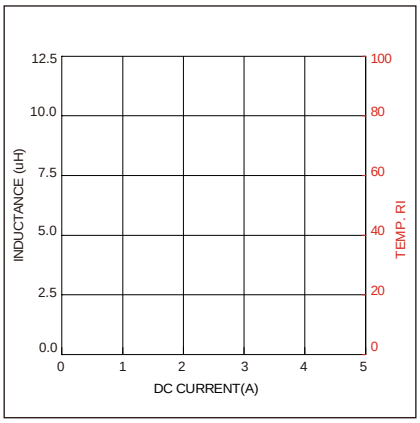






Typical Electrical Characteristics:





Soldering Reflow:

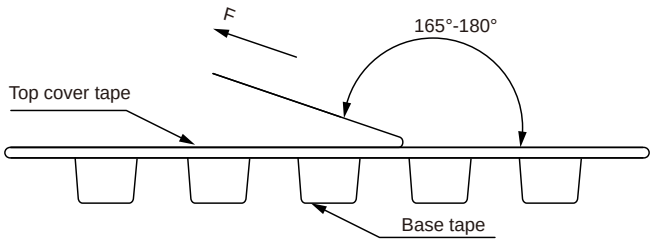
Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

Packaging Information:

Tape Dimension:

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Reel Dimension：[mm]

Packaging Quantity: